EXHIBIT A

Impinj, Inc. v. NXP USA, Inc.

U.S.D.C., Northern District of California, Case No. 4:19-cv-03161-YGR-VKD

JOINT TRIAL EXHIBIT LIST

(January 24, 2024)

Exh. #	Date	Description	Bates Number	Sponsoring Witness	Stipulation to Admit	Objection	Date Admitted
1	2/14/2012	U.S. Patent No. 8,115,597 (Amtmann NDCA Dep. Ex. 7; Peach NDCA Dep. Ex. 2)		Oliver; Peach		402, 403	
2	4/25/2017	U.S. Patent No. 9,633,302 (Heinrich NDCA Dep. Ex. 5)		Heinrich	X		
3	2/14/2012	U.S. Patent No. 8,115,597 File History	IMPINJ_NXP_0000755 - IMPINJ_NXP_0001009	Oliver		402, 403	
4	4/27/2017	U.S. Patent No. 9,633,302 File History	IMPINJ_NXP_0000435 - IMPINJ_NXP_0000567	Heinrich	X		
10	2017	Monza R6 Tag Chip Datasheet - IPJ-W1700, Version 5.0, 2017 Impinj	IMPINJ_NXP_0001540 - IMPINJ_NXP_0001560	Oliver	X		
11	9/28/2018	TechnInsights CircuitVision Analysis Report of the Analog Circuitry and EEPROM on the NXP UCODE8 SL3S1205 RFID Integrated Circuit (Heinrich NDCA Dep. Ex. 16)	IMPINJ_NXP_0002004 - IMPINJ_NXP_0002127	Oliver		402, 403, 106, 802, F	
16	Undated	Impinj Schematics	IMPINJ_NXP_WDTEX_00006191 - IMPINJ_NXP_WDTEX_00006515	Oliver		402, 403	
17	2020	Impinj M700 Series Tag Chip Datasheet - IPJ-M30A-A00; IPJ-M750A-A00, Version 4.0, 2020, Impinj, Inc.	IMPINJ_NXP_WDWASH_00004219 - IMPINJ_NXP_WDWASH_00004242	Oliver	X		
18	10/28/2019	UCODE 8/8M Product data sheet Rev. 3.3 (Amtmann WDWA Dep. Ex. 10)	NXP-IMP-NDCAL-00000354 - NXP-IMP-NDCAL-00000389	Brandl; Amtmann	X		
19	10/17/2016	UCODE8 Analog Requirement Specification, Doc Rev 1.0, 10/17/2016 (Brandl NDCA Dep. Ex. 5; Brandl WDTX Dep. Ex. 6)	NXP-IMP-NDCAL-00005729 - NXP-IMP-NDCAL-00005749	Brandl		402, 403	
21	12/15/2020	UCODE 9 Datasheet - (SL3S1206, Rev. 3.0 - Dec 15, 2020 (Brandl WDTX Dep. Ex. 19; Zenz NDCA Dep. Ex. 6)	NXP-IMP-NDCAL-00207839 - NXP-IMP-NDCAL-00207867	Brandl; Zenz	X		
22	2021	NXP UCODE 9 Fact Sheet re: Accelerated The IoT with UCODE 9 (Brandl NDCA Dep. Ex. 2; Amtmann WDWA Dep. Ex. 9; Amtmann WDTX Dep. Ex. 9; Brandl NDCA Dep. Ex. 13)	NXP-IMP-NDCAL-00207881 - NXP-IMP-NDCAL-00207882	Brandl; Amtmann	X		
49	2013-2019	Revenue for M5 and M6 (2013-2019 1H)	IMPINJ_NXP_0002243 - IMPINJ_NXP_0002243	Dossett		402, 403 (for trial)	
51	5/8/2014	"Impinj Monza R6¶ -- Another Significant Step in RFID's Progress," ChainLink, Bill McBeath, Published on May 8, 2014	IMPINJ_NXP_0046363 - IMPINJ_NXP_0046363	Diorio		402, 403, 802	
52	3/12/2020	"ACE Awards honor innovators in engineering and technology - ACE Awards Names NXP Company of the Year," EDN (Mar 12,2020)	IMPINJ_NXP_0046365 - IMPINJ_NXP_0046369	Diorio		402, 403, 802	
53	8/25/2021	"SMARTRAC Extends Portfolio With New RFID Inlays Based on Monza R6 Chip," Barcode.com (Aug 25, 2021)	IMPINJ_NXP_0046531 - IMPINJ_NXP_0046532	Diorio		402, 403, 802	
54	4/2/2014	"Impinj Introduces Monza® R6 Tag Chip to Drive Retail Applications," yahoo! Finance (Apr 2, 2014)	IMPINJ_NXP_0046533 - IMPINJ_NXP_0046553	Diorio		402, 403, 802	
55	5/8/2014	"Impinj Monza R6 -- Another Significant Step in RFID's Progress," ChainLink, Bill McBeath, Published on May 8, 2014	IMPINJ_NXP_0046554 - IMPINJ_NXP_0046556	Diorio		402, 403, 802	
56	9/27/2017	"Impinj Introduces Monza R6-A RAIN RFID Tag Chip for European Retail Industry," Intrado Globe Newswire (Sept.27, 2017)	IMPINJ_NXP_0046557 - IMPINJ_NXP_0046560	Diorio		402, 403, 802	
57	7/22/2015	"Smartrac extends Portfolio With New RFID Inlays - *Based on the Impinj Monza R6 chip, DogBone and ShortDipole inlays and tags have operating frequencies of 860 z to0 960 MHz,"* L&NW Webpage (July 22, 2015)	IMPINJ_NXP_0046561 - IMPINJ_NXP_0046561	Diorio		402, 403, 802	
58	9/27/2017	"Impinj Introduces Monza R6-A RAIN RFID Tag Chip for European Retain Industry," RFID Solutions Online-AVertMarkets IT Group for RFID Technologies, (Sept, 27, 2017)	IMPINJ_NXP_0046562 - IMPINJ_NXP_0046563	Diorio		402, 403, 802	
59	9/16/2021	"Checkpoint Systems Announces the Launch of First Inlays With The New Impinj M700 Chips," Checkpoint (Sept. 16, 2021)	IMPINJ_NXP_0047183 - IMPINJ_NXP_0047185	Diorio		402, 403, 802	
60	9/16/2021	"New developments in RFID label Ices: an overview," Danny Haak (Sept. 16, 2021)	IMPINJ_NXP_0047186 - IMPINJ_NXP_0047192	Diorio		402, 403, 802	
61	4/13/2021	Press Release - "Invengo Technology announces new inlays and labels for Impinj Monza R6 Chips," Invengo (Apr 13, 2015	IMPINJ_NXP_0047193 - IMPINJ_NXP_0047194	Diorio		402, 403, 802	
62	9/14/2018	"Avery Dennison Introduces two New UHF RFID Inlay Products," Packaging Europe, (Sept. 14, 2018)	IMPINJ_NXP_0047195 - IMPINJ_NXP_0047197	Diorio		402, 403, 802	

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63	9/16/2021	"UHF RFID Inlay: Bling - Ideal for small item-level tagging," Avery Dennison, (Sept. 16, 2021)	IMPINJ_NXP_0047198 - IMPINJ_NXP_0047199	Diorio		402, 403, 802	
64	9/16/2021	"UHF RFID Inlay: Midas Flagtag - Outperforming tag for metallic surfaces and everyday objects," Avery Dennison, (Sept. 16, 2021)	IMPINJ_NXP_0047200 - IMPINJ_NXP_0047200	Diorio		402, 403, 802	
65	9/16/2021	"DELO, Mühlbauer, and Impinj Achieve Milestone in Efficient RAIN RFID Label Manufacturing," DELO Press, (Sept. 16, 2021)	IMPINJ_NXP_0047202 - IMPINJ_NXP_0047204	Diorio		402, 403, 802	
66	7/22/2015	"RFID Chip Tags IoT Aware," EE|Times, Rick Merritt, (Jul 22, 2015)	IMPINJ_NXP_0047205 - IMPINJ_NXP_0047207	Diorio		402, 403, 802	
67	9/16/2021	"Smartrac extends Portfolio With New RFID Inlays - *Based on the Impinj Monza R6 chip, DogBone and ShortDipole inlays and tags have operating frequencies of 860 z to0 960 MHz,"* L&NW Webpage (Sept. 16, 2021))	IMPINJ_NXP_0047208 - IMPINJ_NXP_0047208	Diorio		402, 403, 802	
68	7/23/2020	"Xindeco IOT launches RFID inlay series based on Impinj M700 chips," Abby Wu - Xindeco (RFID) (Published on July 23, 2020)	IMPINJ_NXP_0047209 - IMPINJ_NXP_0047212	Diorio		402, 403, 802	
69	4/20/2016	"SML Group Delivers Retain RFID Inlays and Labels with the Latest Impinj Monza R6 Chip," (Cision PRWeb) (April 20, 2016)	IMPINJ_NXP_0047213 - IMPINJ_NXP_0047214	Diorio		402, 403, 802	
70	5/2/2016	"TexTrace Unveils New Woven RFID Brand Label with Impinj Monza R6-P at RFID Journal Live," (Cision PRWeb) (May 2, 2016)	IMPINJ_NXP_0047215 - IMPINJ_NXP_0047216	Diorio		402, 403, 802	
71	6/2/2015	"SML Group Launches GB3_R6 and MAZE_R6 Inlays Based on Impinj Monza® R6 Chip," RFID Solutions Online (June 2, 2015)	IMPINJ_NXP_0047217 - IMPINJ_NXP_0047220	Diorio		402, 403, 802	
72	7/28/2015	"Century Launches New Generation Inlays with the Innovative Impinj M700 Chips, Century (July 28, 2020)	IMPINJ_NXP_0047221 - IMPINJ_NXP_0047222	Diorio		402, 403, 802	
73		Impinj Product Report Table	IMPINJ_NXP_0047386 - IMPINJ_NXP_0047386	Dossett		402, 403	
74	3/25/2017	"Adient Automates Asset Management with RAIN RFID, Impinj, Inc. (Mar 25, 2017)	IMPINJ_NXP_0049388 - IMPINJ_NXP_0049392	Diorio		402, 403, 802	
75	Undated	List of customer stories from Impinj.com Library	IMPINJ_NXP_0049699 - IMPINJ_NXP_0049701	Diorio		402, 403, 802	
76	Undated	UCODE 7 and UCODE 8 Product Family Shipping Data	NXP-IMP-NDCAL-00206326 - NXP-IMP-NDCAL-00206326	Dossett; Kodritsch		402, 403	
77	3/5/2019	UCODE 7 data sheet, Rev. 4.0 - 5 March 2019 (SL3S1204)	IMPINJ_NXP_0001894 - IMPINJ_NXP_0001933	Amtmann	X		
78	11/19/2018	UCODE 8/8m data sheet, Rev. 3.2 - 19 November 2018 (SL3S1205_15)	IMPINJ_NXP_0001934 - IMPINJ_NXP_0001969	Brandl	X		
79	7/26/2021	ARC Enrolled Inlays	IMPINJ_NXP_0046464 - IMPINJ_NXP_0046497	Thompson		402, 403, 802	
80	Undated	Belt U9 datasheet	IMPINJ_NXP_0046498 - IMPINJ_NXP_0046510	Thompson		402, 403, 802	
81	7/26/2021	Checkpoint Earns ARC Cert with NXP's UCODE 9 IC	IMPINJ_NXP_0046511 - IMPINJ_NXP_0046521	Thompson		402, 403, 802	
82	4/6/2021	SML RFID Launches High Performance GB3U9, one of the first Ucode9 inlays in the market with broad retail certification from University of Auburn RFID Lab (ARC)	IMPINJ_NXP_0046522 - IMPINJ_NXP_0046524	Thompson		402, 403, 802	
83		Scott Emmet Thompson Curriculum Vitae		Thompson		402, 403, 802	
84	1/16/2019	Exhibit E to Initial Expert Report of Dr. Scott E. Thompson Concerning Infringement (Impinj's Supplemental Responses to Defendant's First Set of Interrogatories, January 16, 2019, with Ex. 4 - U.S. Patent No. 9,633,302, charting Monza products)		Thompson		402, 403, MIL	
85		Exhibit F to Initial Expert Report of Dr. Scott E. Thompson Concerning Infringement (Ex. F - Infringement Claim Chart for U.S. Patent No. 9,633,302, charting UCODE 7 and UCODE 8 products)		Thompson		402, 403, 802, MIL	
86	Undated	PI Thickness for Large Pad	NXP-IMP-NDCAL-00048182 - NXP-IMP-NDCAL-00048182	Brandl			

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87	5/5/2014	Teardown sheet (TechInsights CircuitVision Analysis of the Analog Circuitry on the NXP UCODE 7 RFID IC (Heinrich NDCA Dep. Ex. 17))	IMPINJ_NXP_0002128 - IMPINJ_NXP_0002242	Oliver		106, 802, F, 402, 403	
88	5/25/2023	UCODE 9 (AS-5607 / SL3S1206 Images	IMPINJ_NXP_0046525 - IMPINJ_NXP_0046529	Oliver		F	
89	8/30/2013	Pad Shape Presentation - Impinj - Mustang Go/No-go for Kelso, Aug 30th, 2013 (Diorio Dep. Ex. 16)	IMPINJ_NXP_0047294 - IMPINJ_NXP_0047357	Heinrich; Diorio		802	
90	2018	Impinj Monza R6 -A/B/P Wafer Specification - IPJ-W1730-K00; IPJ-W1731-K00; IPJ-W1710-K00, Version 1.0, 2018 Impinj, Inc.	IMPINJ_NXP_DDEL_00002831 - IMPINJ_NXP_DDEL_00002841	Oliver	X		
92	5/2/2016	Impinj Endur Whitepaper, May 2nd, 2016, Impinj, Rev.3.0	IMPINJ_NXP_WDWASH_00004063 - IMPINJ_NXP_WDWASH_00004074	Heinrich		402, 403, 802,	
93	2021	Wafer Specification - Impinj M730 and M750 EndPoint IC Wafer Specification - IPJ-M730A-A00; IPJ-M750A-A00	IMPINJ_NXP_WDWASH_00005050 - IMPINJ_NXP_WDWASH_00005057	Heinrich	X		
94	Undated	M700 post processing steps - 300mm Monza process flow	IMPINJ_NXP_WDWASH_00006520 - IMPINJ_NXP_WDWASH_00006520	Heinrich	X		
95	3/5/2019	UCODE 7 Product data sheet, Rev. 4.0 (Zenz NDCA Dep. Ex. 4)	NXP-IMP-NDCAL-00000314 - NXP-IMP-NDCAL-00000353	Amtmann, Zenz	X		
96	3/6/2019	Datasheet (7m)	NXP-IMP-NDCAL-00000390 - NXP-IMP-NDCAL-00000423	Amtmann	X		
97	11/24/2014	Avery documents	NXP-IMP-NDCAL-00005063 - NXP-IMP-NDCAL-00005074	Zach		Description does not match document, 402, 403,	
99	Undated	UCODE 7 & Part Number and FAB Name Report	NXP-IMP-NDCAL-00206325 - NXP-IMP-NDCAL-00206325	Brandl	X		
100	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206372 - NXP-IMP-NDCAL-00206372	Zenz	X		
101	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206373 - NXP-IMP-NDCAL-00206373	Zenz	X		
102	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206374 - NXP-IMP-NDCAL-00206374	Zenz	X		
103	12/24/2016	Large Pad Product Analysis Report	NXP-IMP-NDCAL-00206389 - NXP-IMP-NDCAL-00206398	Zenz	X		
104	Undated	Bump Mask Drawing	NXP-IMP-NDCAL-00206456 - NXP-IMP-NDCAL-00206462	Zenz	X		
105	4/10/2020	Gold Bump Qualification Report	NXP-IMP-NDCAL-00206463 - NXP-IMP-NDCAL-00206479	Zenz	X		
106	5/25/2020	Bump Package Construction Analysis	NXP-IMP-NDCAL-00206480 - NXP-IMP-NDCAL-00206493	Zenz	X		
107	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206497 - NXP-IMP-NDCAL-00206497	Zenz	X		
108	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206502 - NXP-IMP-NDCAL-00206502	Zenz	X		
109	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206503 - NXP-IMP-NDCAL-00206503	Zenz	X		
110	Undated	Bump size spreadsheet	NXP-IMP-NDCAL-00206504 - NXP-IMP-NDCAL-00206504	Zenz	X		
111	2/7/2017	Delta Qualification Report	NXP-IMP-NDCAL-00206505 - NXP-IMP-NDCAL-00206514	Zenz	X		
112	Undated	Application Sheet	NXP-IMP-NDCAL-00206546 - NXP-IMP-NDCAL-00206546	Zenz	X		
113	5/5/2021	Dicing Presentation	NXP-IMP-NDCAL-00206547 - NXP-IMP-NDCAL-00206547	Zenz	X		

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114	5/11/2020	Blade Dicing Process	NXP-IMP-NDCAL-00206550 - NXP-IMP-NDCAL-00206550	Zenz	X		
115	Undated	Bump Measurement Spreadsheet	NXP-IMP-NDCAL-00206551 - NXP-IMP-NDCAL-00206551	Zenz	X		
116	11/13/2020	Assembly Report	NXP-IMP-NDCAL-00206552 - NXP-IMP-NDCAL-00206552	Zenz	X		
117	8/6/2020	Wafer Qualification Report	NXP-IMP-NDCAL-00207817 - NXP-IMP-NDCAL-00207838	Zenz	X		
119	Undated	UCODE 7 Bump Image	NXP-IMP-NDCAL-00209510 - NXP-IMP-NDCAL-00209510	Thompson	X		
120	Undated	UCODE 8 Large Pad Image	NXP-IMP-NDCAL-00209511 - NXP-IMP-NDCAL-00209511	Thompson	X		
121	8/17/2021	Bump Discoloration Verification Report	NXP-IMP-NDCAL-00209652 - NXP-IMP-NDCAL-00209665	Thompson	X		
124	2/5/2020	*NXP USA, Inc. v. Impinj, Inc.,* IPR2020-00516, Paper 1, Petition for Inter Partes Review, Title: RFID Integrated Circuits With Channels for Reducing Misalignment Re: U. S. Patent No. 9,633,302 (PTAB)		Thompson		402, 403, Agreed MIL	
126		*NXP USA, Inc. v. Impinj, Inc.,* IPR2020-00516, Exhibit 2001, Declaration of Scott Thompson		Thompson		402, 403, 802	
127	1965	Moore, G. E., Cramming More Components on Integrated Circuits, Electronics, vol. 38, no. 8, p. 114 (1965)		Thompson		802	
128	1975	Moore, G. E., Progress in Digital Integrated Electronics, IEDM Tech. Digest, vol. 21, p. 11 (1975)		Thompson		802	
129	2006	Scott E. Thompson, Srivatsan Parthasarathy, Moore's law: the future of Si microelectronics, Materials Today, vol. 9, issue 6, p. 20–25 (June 2006)		Thompson		802	
130	2008	U.A. Bakshi and A.P. Godse, Linear Integrated Circuits at 1-1 (3d ed. 2008) (excerpts) (IPR2020-00516 Ex. 2003)		Thompson		802	
131	2001	Michael Quirk & Julian Serda, Semiconductor Manufacturing Technology at 5 (2001), Attachment 2 to Declaration of Scott E. Thompson in Support of Petition for *Inter Partes* Review of U.S. Patent No. 7,538,444 (IPR2021-00003 Ex. 1007)	IMPINJ_NXP_WDWASH_00004887 - IMPINJ_NXP_WDWASH_00004899	Thompson		802	
132	Multiple	Daniel M. Dobkin, The RF in RFID: Passive UHF RFID in Practice at 9 (2008) (excerpts) (IPR2020-00516 Ex. 2005)		Thompson		802	
133	2010	Holmberg et al., E-maintenance at 200 (2010)		Thompson		802	
134	2018	Simone Zuffanelli, Antenna Design Solutions for RFID Tags Based on Metamaterial-Inspired Resonators and Other Resonant Structures at 16 (2018)		Thompson		802	
135		Advances in Embedded and Fan-Out Wafer Level Packaging Technologies at 419		Thompson		802	
136	5/4/2010	U.S. Patent No. 7,709,954		Thompson		402, 403	
137	2008	R. Doering & Y Nishi., Handbook of Semiconductor Manufacturing Technology, at 16-1 (2d ed. 2008)		Thompson		802	
138	7/29/2018	Manufacturing Lounge, Additive vs. subtractive manufacturing – what's the difference?, http://www.manufacturinglounge.com/additive-vs-subtractive-manufacturing-whatsthe- difference/ (July 29, 2018)		Thompson		402, 403	
139	2/28/2019	DigitalAlloys, Comparison of Additive Manufacturing & CNC Machining, https://www.digitalalloys.com/blog/comparison-additive-manufacturing-cnc-machining/ (Feb. 28, 2019)		Thompson		402, 403	
141	8/20/2013	U.S. Patent No. 8,511,569		Thompson		402, 403, 802	

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142	Undated	RFIDeal, https://www.cbinsights.com/company/rfideal		Thompson		402, 403, 802	
143	2013	Passive Full-Wave MOSFET Rectifiers for Electromagnetic Harvesting Available at: https://uwspace.uwaterloo.ca/bitstream/handle/10012/7722/Yilmaz_Mehmet.pdf?sequence=1&isAllowed=y		Thompson		402, 403, 802	
144	2007	Semiconductor Packaging Technologies Available at https://www.nxp.com/files-static/wireless_comm/doc/white_paper/WIREBONDBYNDWP.pdf		Thompson	X		
145	6/18/2020	Structure and Properties of Additive Manufactured Polymer Components - Available at: https://books.google.com/books?id=HDLXDwAAQBAJ&pg=PA37&dq=carbon+black+commonly+used+printed+conductors&hl=en&newbks=1&newbks_redir=0&source=gb_mobile_search&sa=X&ved=2ahUKEwi307XBwrX5AhXeSDABHTdRB1s4ChDoAXoECAMQAw#v=onepage&q=carbon%20black%20commonly%20used%20printed%20conductors&f=false		Thompson		802	
146	2001	The back-end process: Step 7 – Solder bumping step by step Available at https://sst.semiconductor-digest.com/2001/07/the-back-end-process-step-7-solder-bumping-step-by-step/		Thompson		402, 403, 802	
147	Undated	Standard FlipChip – Repassivation (PBO or BCB) Available at https://www.flipchip.com/sfcrepass.html		Thompson		402, 403, 802	
149	9/27/2017	"Impinj Introduces Monza R6-A RAIN RFID Tag Chip for European Retail Industry," Intrado Globe Newswire (Sept. 27, 2017)	IMPINJ_NXP_0046557 - IMPINJ_NXP_0046560	Diorio		402, 403, 802	
150	10/21/2020	"IMPINJ Digital Life for Everyday Items - 4Q20 Endpoint IC Summit," Impinj, (Oct 21, 2020)	IMPINJ_NXP_0046836 - IMPINJ_NXP_0046888	Diorio		402, 403, 802	
151	1/27/2021	"IMPINJ Digital Life for Everyday Items - 1Q210 Endpoint IC Summit," Impinj, (Jan 27, 2021))	IMPINJ_NXP_0046889 - IMPINJ_NXP_0046957	Diorio		402, 403, 802	
154	4/10/2021	"Endpoint IC Strategy," Impinj (Apr 10, 2021)	IMPINJ_NXP_0047253 - IMPINJ_NXP_0047293	Diorio		802	
155	11/19/2014	Meeting Notes Avery-NXP, UCODE 8 specification, Greensboro, 2014/11/19 (Zenz NDCA Dep. Ex. 11)	NXP-IMP-NDCAL-00005113 - NXP-IMP-NDCAL-00005115	Zach; Zenz	X		
156	11/23/2006	PowerPoint Presentation: "NXP UCODE 8 Product Options - Cost - Bizz Figures"	NXP-IMP-NDCAL-00005235 - NXP-IMP-NDCAL-00005235	Zach	X		
157	9/10/2014	UCODE 8 Status report & next steps, PowerPoint presentation by Hermann Zach (Brandl NDCA Dep. Ex. 10; Zach WDTX Dep. Ex. 5) (printed from native file)	NXP-IMP-NDCAL-00005238 - NXP-IMP-NDCAL-00005238	Zach; Brandl		402, 403	
158	3/3/2015	UCODE 8 Customer Requirements Specification, Doc Rev 1 Draft - 3 Mar 2015 (Bischof Dep. Ex. 3; Zenz NDCA Dep. Ex. 9)	NXP-IMP-NDCAL-00004848 - NXP-IMP-NDCAL-00004873	Zach; Bischof; Zenz		402, 403	
159	7/24/2009	HTCICC64 Product Data Sheet, HITAG µ RO64 transponder IC, Rev 3.1 - July 24, 2009 (176431)	NXP-IMP-NDCAL-00209666 - NXP-IMP-NDCAL-00209678	Thompson	X		
160	3/18/2020	HITAG µ ISO 18000 transponder IC Product Data Sheet, Rev. 3.0 - Mar 18, 2020 (184430)	NXP-IMP-NDCAL-00209679 - NXP-IMP-NDCAL-00209722	Thompson	X		
204	7/11/2017	Impinj 3Q17 Monza Summit, powerPoint presentation dated July 11, 2017 (Dossett Dep. Ex. 3, dated July 11, 2017	IMPINJ_NXP_0046694	Dosset, Diorio, Kindler		402, 403, 802	
205	10/5/2017	Impinj 4Q17 Monza Summit, PowerPoint presentation dated October 5, 2017 (Dossett Dep. Ex. 4) (printed from native file)	IMPINJ_NXP_0046695	Dosset, Diorio, Kindler		402, 403, 802	
206	7/15/2019	Impinj 3Q19 Silicon Summit, PowerPoint presentation dated July 15, 2019 (Dossett Dep. Ex. 9) (printed from native file)	IMPINJ_NXP_0046702	Dosset, Diorio, Kindler		402, 403, 802	
207	4/20/2021	Impinj 2Q21 Endpoint IC Summit dated April 20, 2021 (Dossett Dep. Ex. 10)	IMPINJ_NXP_0046958 - IMPINJ_NXP_0047015	Dossett		402, 403, 802	

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208	7/15/2021	Impinj 3Q21 Endpoint IC Summit dated July 15, 2021 (Dossett Dep. Ex. 11)	IMPINJ_NXP_0047016 - IMPINJ_NXP_0047077	Dossett		402, 403, 802	
209	9/6/2021	Maui Marketing Requirements Document	IMPINJ_NXP_0047092 - IMPINJ_NXP_0047098	Oliver		402, 403, 802	
215	2022	Impinj Invoice Specification (through Q3 2022) (Dannels WDTX Dep. Ex. 4)	IMPINJ_NXP_0049961	Kindler; Diorio		402, 403, 802	
216	2018	Impinj Monza R6-A Tag Chip Datasheet, 2018	IMPINJ_NXP_DDEL_00002444 - IMPINJ_NXP_DDEL_00002463	Oliver	X		
217	2018	Impinj Monza R6-P Tag Chip Datasheet, 2018	IMPINJ_NXP_DDEL_00002464 - IMPINJ_NXP_DDEL_00002485	Oliver	X		
218	2017	Impinj Monza R6 Tag Chip Datasheet, Version 5.0 (Stanford WDWA Dep. Ex. 3)	IMPINJ_NXP_DDEL_00002584 - IMPINJ_NXP_DDEL_00002604	Oliver; Stanford	X		
219	2018	Impinj Monza R6-B Tag Chip Datasheet, 2018	IMPINJ_NXP_DDEL_00002605 - IMPINJ_NXP_DDEL_00002623	Oliver	X		
221	2020	RAIN Alliance: Global Markets and Applications for RAIN RFID Solutions A Market Research Report dated October 2020	IMPINJ_NXP_WDTEX_00006640	Dosset, Diorio, Kindler		802	
222	Multiple	RFID Forecasts, Players and Opportunities: 2016-2026 - IDTechEx	IMPINJ_NXP_WDTEX_00006641 - IMPINJ_NXP_WDTEX_00006834	Dosset, Diorio, Kindler		802	
223	Multiple	RFID Forecasts, Players, and Opportunities 2022-2032 - IDTechEx	IMPINJ_NXP_WDTEX_00007555 - IMPINJ_NXP_WDTEX_00007837	Dosset, Diorio, Kindler		802	
224	Undated	Impinj Finished Goods Inventory (Dannels WDWA Dep. Ex. 6)	IMPINJ_NXP_WDTEX_00009504	Dosset, Diorio, Kindler		402, 403, 802	
225	5/9/2017	UCODE 8 Omnichannel redtail data at unmatched speed and accuracy, RFiD Journal LIVE!, PowerPoint presentation by Kurt Bischof (Bischof NDCA Dep. Ex. 6) (printed from native file)	NXP-IMP-NDCAL-00004874	Bischof	X		
226	11/11/2014	Meeting Notes Avery-NXP, UCODE8 Specification dated November 10 – 11, 2014 (Zach NDCA Dep. Ex. 2)	NXP-IMP-NDCAL-00005058 - NXP-IMP-NDCAL-00005062	Zach	X		
227	12/1/2014	UCODE 8 dated December 1, 2014 (Kodritsch Dep. Ex. 3)	NXP-IMP-NDCAL-00005148	Kodritsch	X		
228	1/30/2015	Meeting Notes SML-NXP dated January 30, 2015 (Kodritsch Dep. Ex. 5)	NXP-IMP-NDCAL-00005170	Kodritsch		402, 403, 802	
229	3/14/2016	NXP Customer Requirements Specification UCODE 8 dated March 14, 2016 (Bischof Dep. Ex. 4)	NXP-IMP-NDCAL-00005621 - NXP-IMP-NDCAL-00005655	Bischof	X		
230	Undated	Native Excel: NXP-IMP-NDCAL-00206211.xlsx	NXP-IMP-NDCAL-00206211 -	Dosset, Diorio, Kindler		402, 403, 802, 1001, F	
231	5/9/2017	NXP Revolutionizes Retail Customer Experiences, Launches Industry's Most Power Efficient Global RAIN RFID Chip for Omnichannel Retail Data dated May 9, 2017 (Kodritsch Dep. Ex. 7)	NXP-IMP-NDCAL-00206220 - NXP-IMP-NDCAL-00206221	Kodritsch	X		
232	Undated	NXP RFID Presentation, by Ralf Kodritsch (Kodritsch Dep. Ex. 4)	NXP-IMP-NDCAL-00206227 - NXP-IMP-NDCAL-00206251	Kodritsch	X		
233	2017	Omnichannel Retail Data at unmatched Speed and Accuracy, dated April 2017 (Brandl Dep. Ex. 1)	NXP-IMP-NDCAL-00206253 - NXP-IMP-NDCAL-00206254	Brandl	X		
234	3/2019	Improving the product journey with UCODE® 8, PowerPoint presentation dated March 2019 (Bischof Dep. Ex. 7; Kodritsch NDCA Dep. Ex. 14) (native file)	NXP-IMP-NDCAL-00206255 - NXP-IMP-NDCAL-00206255	Bischof; Kodritsch	X		
235	3/26/2014	Impinj Enduro Technology dated March 26, 2014 (Diorio Dep. Ex. 17; Kodritsch NDCA Dep. Ex. 2; Zenz NDCA Dep. Ex. 8)	NXP-IMP-NDCAL-00206329 - NXP-IMP-NDCAL-00206340	Diorio; Kodritsch; Zenz		402, 403, 802	
236		M7x0 Fighting Guide Internal Version, by Hermann Zach (Kodritsch NDCA Dep. Ex. 15; Zach WDTX Dep. Ex. 10) (printed from native file)	NXP-IMP-NDCAL-00208032	Zach	X		

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237	August 2016	NXP UCODE 9 – Concept Working Document Presentation dated August 2018	NXP-IMP-NDCAL-00208058	Zach; Kodritsch	X		
238	11/13/2017	NXP UCODE 9, PowerPoint presentation dated November 13, 2017 (Bischof Dep. Ex. 10) (printed from native file)	NXP-IMP-NDCAL-00208068	Bischof; Zach	X		
239	11/8/2018	NXP UCODE 9 – PI Gate Presentation dated November 8, 2018 (Brandl Dep. Ex. 11; Zenz NDCA Dep. Ex. 10) (printed from native file)	NXP-IMP-NDCAL-00208076	Brandl; Zach	X		
240	2020	UCODE 9 Product Data Sheet, 2020 (Brandl Dep. Ex. 15)	NXP-IMP-NDCAL-00208347 - NXP-IMP-NDCAL-00208375	Brandl	X		
241		Excel spreadsheet re: Smart label IC - Customer Requirements Specification (Kodritsch NDCA Dep. Ex. 9) (native file)	NXP-IMP-NDCAL-00208466	Zach; Kodritsch	X		
250	5/23/2022	Dielectric constant, RFID Journal. (https://www.rfidjournal.com/glossary/dielectric-constant, viewed on May 23, 2022.)		Kindler		402, 403, 802	
251	3/27/2022	EPS News: And the Winner Is… Ace Awards Honor Best in Engineering & Technology dated July 22, 2015. (https://epsnews.com/2015/07/22/and-the-winner-is-ace-awards-honor-best-in-engineering- technology/, viewed on May 27, 2022.)		Oliver, Diorio		402, 403, 802	
267	4/29/2022	Impinj Monza 5 Tag Chip Datasheet. (https://support.impinj.com/hc/en-us/articles/202756948-Monza-5-Tag-Chip-Datasheet, viewed on April 29, 2022.)		Oliver, Diorio		402,403,802	
269	4/29/2022	Impinj Monza R6 Series RAIN RFID Tag Chips Product Brief. (https://support.impinj.com/hc/article_attachments/4412848968723/Impinj-Monza-R6-Series-Product-Brief-121421.pdf, viewed on April 29, 2022.)		Oliver, Diorio		802	
288	5/10/2017	NXP to Release More Sensitive UHF Chip With New Functionality dated May 10, 2017. (https://www.rfidjournal.com/nxp-to-release-more-sensitive-uhf-chip-with-new-functionality, viewed on June 15, 2022.)		Oliver, Diorio		402, 403, 802, F, NP	
289	4/29/2022	NXP UCODE 8 Fact Sheet. (https://www.nxp.com/docs/en/fact-sheet/UCODE8LF.pdf, viewed on April 29, 2022.)	NXP-IMP-NDCAL-00000424 - NXP-IMP-NDCAL-00000425	Oliver, Diorio	X		
291	4/28/2022	NXP UCODE 9 Fact Sheet. (https://www.nxp.com/docs/en/fact-sheet/UCODE9FSA4.pdf, viewed on April 28, 2022.)		Oliver, Diorio	X		
332	3/17/2015	Science Vision Circuit Analysis Report, IPJ-W1700 - Monza R6 Tag Chip (Amtmann NDCA Dep. Ex. 2)	NXP-IMP-DDEL-00011904 - NXP-IMP-DDEL-00012090	Amtmann		402, 403, 106, 802, 1001, F, MIL	
333	2010	CircuitVision Analysis on the Analog Circuitry of the Impinj Monza RFID Tag (Amtmann NDCA Dep. Ex. 3)	NXP-IMP-DDEL-00011424 - NXP-IMP-DDEL-00011588	Amtmann		402, 403, 106, 802, 1001, F, MIL	
334	4/22/2011	NXP Failure Analysis Report - Competitor analyse [sic] Impinj M5 RFID chip (Amtmann NDCA Dep. Ex. 4)	NXP-IMP-WDWASH-00013619 - NXP-IMP-WDWASH-00013623	Amtmann		402, 403, MIL	
335	3/3/2015	Customer Requirements Specification UCODE 8 - Doc Rev 1 Draft (Amtmann NDCA Dep. Ex. 6)	NXP-IMP-NDCAL-00005441 - NXP-IMP-NDCAL-00005466	Amtmann	X		
336	10/3/2014	UCODE 8 EcoSystem-Review (Amtmann NDCA Dep. Ex. 8) (native file)	NXP-IMP-NDCAL-00005239	Amtmann	X		
337	9/28/2016	Competitor Analysis Report PDC NYM Impinj Monza R6 RFID Tag, by Claud van Oers (Amtmann NDCA Dep. Ex. 11; Brandl WDTX Dep. Ex. 24)	NXP-IMP-NDCAL-00004812 - NXP-IMP-NDCAL-00004828	Amtmann; Brandl		402, 403, MIL	
338	8/10/2015	Email from Hermann Zach to Ralf Kodritsch, et al. re Arizon Impinj R6 wafer + Labels (Amtmann NDCA Dep. Ex. 12; Kodritsch NDCA Dep. Ex. 6)	NXP-IMP-WDWASH-00013610	Amtmann; Kodritsch		402, 403, MIL	
339	3/17/2015	Structure Analysis Report, IPJ-W1700 Cross Section (Amtmann NDCA Dep. Ex. 13)	NXP-IMP-DDEL-00012091 - NXP-IMP-DDEL-00012111	Amtmann		402, 403, 802, 1001, MIL	
340	9/25/2019	UCODE 9 - Chip Options - High Level Descript + Estimates, by Hermann Zach (Amtmann NDCA Dep. Ex. 14) (native file)	NXP-IMP-NDCAL-00208060 -	Amtmann	X		
343	2/2/2015	Email thread from Franz Amtmann to Robert Spindler et a. the Mory part: ICAnlysisCapability_ScienceVision_HongYuan ROSE (Amtmann WDWA Dep. Ex. 17)	NXP-IMP-WDWASH-00013789 - NXP-IMP-WDWASH-00013798	Amtmann		402, 403	

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348	Undated	Excel spreadsheet, with first tab named "UHF Market Details" (Bischof NDCA Dep. Ex. 1) (native file)	NXP-IMP-NDCAL-00206211	Bischof		402, 403, 802, 1001, F	
349	2/22/2015	UCODE 8, PowerPoint presentation by Kurt Bischof (Bischof NDCA Dep. Ex. 2) (printed from native file)	NXP-IMP-NDCAL-00005233	Bischof	X		
353	Undated	Typewritten notes re meeting between Arizon and NXP, Meeting Location: Arizon - Yangzhou GC (Bischof NDCA Dep. Ex. 11)	NXP-IMP-NDCAL-00005149	Bischof	X		
356	12/9/2008	BiC UCODE Customer Requirements Specification, Doc Rev 2 Approved (Brandl WDTX Dep. Ex. 2)	NXP-IMP-NDCAL-00005275 - NXP-IMP-NDCAL-00005288	Brandl	X		
367	10/20/2016	UCODE 8 Validation, Characterization and Qualification Report, Doc Rev 0.1 (Brandl WDTX Dep. Ex. 21)	NXP-IMP-NDCAL-00004529 - NXP-IMP-NDCAL-00004634	Brandl	X		
368	3/21/2018	UCODE 8 - Validation Deep Dive, PowerPoint presentation by Gerald Müller (Brandl WDTX Dep. Ex. 23)	NXP-IMP-NDCAL-00149213	Brandl	X		
369	January 2015	UCODE8 Data integrity of U8 - proposal + slides of brainstorming meeting (December 2015 [sic]) and meeting minutes, Powerpoint presentation (Brandl WDTX Dep. Ex. 25) (printed from native file)	NXP-IMP-NDCAL-00005925	Brandl	X		
370		Impinj's Notice of Deposition of NXP pursuant to FRCP 30(b)(6) (Kodritsch NDCA Dep. Ex. 1)				402, 403, 806, F	
371		UCODE 8 PowerPoint slide deck by Hermann Zach (Kodritsch NDCA Dep. Ex. 3) (printed from native file)	NXP-IMP-NDCAL-005148	Zach	X		
372		Photo re: R6_wafer_HR	NXP-IMP-WDWASH-00013345 - NXP-IMP-WDWASH-00013345	Kodritsch		402, 403	
373		Photo re: R6_wafer_Label_HR.jpg	NXP-IMP-WDWASH-00013346 - NXP-IMP-WDWASH-00013346	Kodritsch		402, 403	
374		Photo re: R6_wafer_Label_LR.jpg	NXP-IMP-WDWASH-00013347 - NXP-IMP-WDWASH-00013347	Kodritsch		402, 403	
375		Photo re: R6_wafer_LR.jpg	NXP-IMP-WDWASH-00013348 - NXP-IMP-WDWASH-00013348	Kodritsch		402, 403	
376	5/24/2017	UCODE 9 (or 8s?) Objectives slide deck by NXP (Kodritsch NDCA Dep. Ex. 10) (native file)	NXP-IMP-NDCAL-00208451	Kodritsch	X		
379		Avery Dennison Purchase Order to NXP, re NXP UCODE 8 (Kodritsch WDWA Dep. Ex. 6)	NXP-IMP-WDTEX-00017400 - NXP-IMP-WDTEX-00017402	Kodritsch	X		
380		Avery Dennison Purchase Order to NXP re NXP UCODE 8 (Kodritsch WDWA Dep. Ex. 7)	NXP-IMP-WDTEX-00017435 - NXP-IMP-WDTEX-00017437	Kodritsch	X		
381		Smartrac Purchase Order to NXP re UCODE7 (Kodritsch WDWA Dep. Ex. 8)	NXP-IMP-WDTEX-00017211 - NXP-IMP-WDTEX-00017214	Kodritsch	X		
382		Excel spreadsheet printout from native file re IDTechEX FC 2017(Kodritsch WDWA Dep. Ex. 9)		Kodritsch	X		
383		Distributor Agreement between NXP Semiconductors Netherlands B.V. and Mouser Electronics (Kodritsch WDWA Dep. Ex. 11)	NXP-IMP-WDTEX-00018192 - NXP-IMP-WDTEX-00018210	Kodritsch		402, 403	
384		Distributor Agreement between NXP Semiconductors Netherlands B.V. and Vitec Holdings (Kodritsch WDWA Dep. Ex. 12)	NXP-IMP-WDTEX-00017830 - NXP-IMP-WDTEX-00017850	Kodritsch		402, 403	
385		Excel spreadsheet re Distributor Resales of Selected Parts (2016 - 2022 to date) (hard copy printouts from native file) (Kodritsch WDWA Dep. Ex. 13)		Kodritsch		402, 403, 1001	
386		Excel spreadsheet (hard copy printouts from native file) (Kodritsch WDWA Dep. Ex. 14)		Kodritsch	X		
390	Undated	Layout of the pads on UCODE 8 and UCODE 9 (Zenz NDCA Dep. Ex. 7)	NXP-IMP-NDCAL-00208499	Zenz	X		
391	11/11/2014	Avery-NXP UCODE 8 Spec discussion - 11.11.2014 meeting notes (Zach NDCA Dep. Ex. 1; Zach WDTX Dep. Ex. 4; Stott NDCA Dep. Ex. 6)	NXP-IMP-NDCAL-00005053 - NXP-IMP-NDCAL-00005054	Zach; Stott	X		
398		UCODE 8 + UCODE 8 IP Study (Zach WDTX Dep. Ex. 6) (printed from native file)	NXP-IMP-NDCAL-00005237	Zach	X		
401		UCODE 9 - TO B1 Major Milestone Presentation PowerPoint slide deck, by Robert Spindler (Zach WDTX Dep. Ex. 9) (printed from native file)	NXP-IMP-NDCAL-00208448	Zach	X		

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408	2015-2019	Impinj Invoice Specification (through Q1 2021) (native file) (Dannels NDCA Dep. Ex. 3)	IMPINJ_NXP_0046530 - IMPINJ_NXP_0046530	Dosset, Diorio, Kindler	X		
409	2015-2019	Impinj Invoice Specification (through Q1 2021) (hard copy printout) (Dannels NDCA Dep. Ex. 4)	IMPINJ_NXP_0046530 - IMPINJ_NXP_0046530	Dosset, Diorio, Kindler	X		
410		Excel spreadsheet (native file) unnumbered (Dannels WDWA Dep. Ex. 3)		Dosset, Diorio, Kindler	X		
411		Impinj Invoice Specification (through Q3 2022) (Dannels WDWA Dep. Ex. 4)	IMPINJ_NXP_WDWASH_00028295	Dosset, Diorio, Kindler	X		
412	1/16/2015	Email from Harley Heinrich to Tan Mau Wu re: Beveled RF pads (Heinrich NDCA Dep. Ex. 6)	IMPINJ_NXP_0001868 - IMPINJ_NXP_0001868	Heinrich		802	
413	3/18/2010	NXP HITAG µ ISP 18000 transponder IC Product data sheet PUBLIC Rev. 3.0 - 18 March 2010 (Heinrich NDCA Dep. Ex. 8)	-	Thompson	X		
416		NXP Semiconductors NV Master File (Rajen WDTX Dep. Ex. 7)	NXP-IMP-WDTEX-00018855 - NXP-IMP-WDTEX-00018894	Rajen		402, 403, 802	
417		NXP USA Distribution Agreement (Rajen WDTX Dep. Ex. 9)	NXP-IMP-WDTEX-00018749 - NXP-IMP-WDTEX-00018766	Rajen		402, 403, 802	
418	2021	NXP Worldwide Sales Data (through 2021) (Rajen WDTX Dep. Ex. 16) (printed from native file)	NXP-IMP-WDTEX-00018787	Rajen; Kindler		402, 403	
419		NXP Distributor Data (Rajen WDTX Dep. Ex. 19)	NXP-IMP-WDTEX-00017135	Rajen		402, 403, 1001	
423	11/19/2018	UCODE 8 Datasheet, version 3.2	NXP-IMP-NDCAL-00004173 - NXP-IMP-NDCAL-00004208	Amtmann	X		
444		UCODE Pad Placement Images	NXP-IMP-NDCAL-00209054 - NXP-IMP-NDCAL-00209071	Zenz	X		
448	Undated	UCODE 9 Mask Layouts	NXP-IMP-NDCAL-00209123 - NXP-IMP-NDCAL-00209127	Zenz	X		
449		Adient Automates Asset Management with RAIN RFID	IMPINJ_NXP_WDWASH_00028296 - IMPINJ_NXP_WDWASH_00028300	Diorio		402, 403, 802	
450		Aertssen Logistics Picks Assets Faster with RAIN RFID Asset Management	IMPINJ_NXP_WDWASH_00028301 - IMPINJ_NXP_WDWASH_00028305	Diorio		402, 403, 802	
451		Alvero Manages Rental Asset Warehouse with RAIN RFID	IMPINJ_NXP_WDWASH_00028306 - IMPINJ_NXP_WDWASH_00028310	Diorio		402, 403, 802	
452		Asset Recovery Specialists Use RAIN RFID Technology to Save on Labor and Improve Supply Chain	IMPINJ_NXP_WDWASH_00028311 - IMPINJ_NXP_WDWASH_00028315	Diorio		402, 403, 802	
453		Berendsen Improves Laundry Facility Efficiency with RAIN RFID	IMPINJ_NXP_WDWASH_00028316 - IMPINJ_NXP_WDWASH_00028320	Diorio		402, 403, 802	
454		Brussels Airport Allows Flyers to Track Their Luggage with Impinj	IMPINJ_NXP_WDWASH_00028321 - IMPINJ_NXP_WDWASH_00028324	Diorio		402, 403, 802	
455		Carvana Uses RAIN RFID to Improve Car Buying Experience	IMPINJ_NXP_WDWASH_00028325 - IMPINJ_NXP_WDWASH_00028329	Diorio		402, 403, 802	
456		Chemours Automates Their Yard Management with IoT, Kaleris and Impinj	IMPINJ_NXP_WDWASH_00028330 - IMPINJ_NXP_WDWASH_00028334	Diorio		402, 403, 802	
457		China Outfitters Increases Operational Efficiency with RAIN RFID	IMPINJ_NXP_WDWASH_00028335 - IMPINJ_NXP_WDWASH_00028339	Diorio		402, 403, 802	
458		Cisco Tracks and Manages Data Center IT Assets with RAIN RFID	IMPINJ_NXP_WDWASH_00028340 - IMPINJ_NXP_WDWASH_00028343	Diorio		402, 403, 802	
459		Coca-Cola Improves Drink Dispenser Experience	IMPINJ_NXP_WDWASH_00028344 - IMPINJ_NXP_WDWASH_00028347	Diorio		402, 403, 802	
460		Cooperative Hoogstraten Tracks From Farm to Table with RAIN RFID	IMPINJ_NXP_WDWASH_00028348 - IMPINJ_NXP_WDWASH_00028352	Diorio		402, 403, 802	

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461		CSA Hospital Manages Surgical Supplies with Smart Cabinet	IMPINJ_NXP_WDWASH_00028353 - IMPINJ_NXP_WDWASH_00028356	Diorio		402, 403, 802	
462		Cuploop Makes Reusing Packages Faster and Easier with RAIN RFID	IMPINJ_NXP_WDWASH_00028357 - IMPINJ_NXP_WDWASH_00028361	Diorio		402, 403, 802	
463		Dana Incorporated Achieves 100% Parts Traceability	IMPINJ_NXP_WDWASH_00028362 - IMPINJ_NXP_WDWASH_00028366	Diorio		402, 403, 802	
464		Elis Improves Workflows by Automating Laundry Tracking & Sorting	IMPINJ_NXP_WDWASH_00028367 - IMPINJ_NXP_WDWASH_00028370	Diorio		402, 403, 802	
465		Emergency Agency Plans Ahead with RAIN RFID Asset Tracking	IMPINJ_NXP_WDWASH_00028371 - IMPINJ_NXP_WDWASH_00028375	Diorio		402, 403, 802	
466		Eurocopter Asset Tracking with RAIN RFID	IMPINJ_NXP_WDWASH_00028376 - IMPINJ_NXP_WDWASH_00028380	Diorio		402, 403, 802	
467		Euro Pool Increased Warehouse Efficiency with RAIN RFID at the Dock Door	IMPINJ_NXP_WDWASH_00028381 - IMPINJ_NXP_WDWASH_00028384	Diorio		402, 403, 802	
468		Faurecia Creates the Factory of the Future with RAIN RFID	IMPINJ_NXP_WDWASH_00028385 - IMPINJ_NXP_WDWASH_00028389	Diorio		402, 403, 802	
469		Haier Automates Processes, Improves Manufacturing with RAIN RFID	IMPINJ_NXP_WDWASH_00028390 - IMPINJ_NXP_WDWASH_00028394	Diorio		402, 403, 802	
470		Hamni Uses RAIN RFID for Pharma Supply Chain Management	IMPINJ_NXP_WDWASH_00028395 - IMPINJ_NXP_WDWASH_00028399	Diorio		402, 403, 802	
471		Heathrow Airport Pilots RAIN RFID Project to Track Luggage Carts	IMPINJ_NXP_WDWASH_00028400 - IMPINJ_NXP_WDWASH_00028404	Diorio		402, 403, 802	
472		Heilan Home Streamlines Logistics and Retail Operations with RAIN RFID	IMPINJ_NXP_WDWASH_00028405 - IMPINJ_NXP_WDWASH_00028409	Diorio		402, 403, 802	
473		Hospital Saves Time and Resources with RAIN RFID	IMPINJ_NXP_WDWASH_00028410 - IMPINJ_NXP_WDWASH_00028414	Diorio		402, 403, 802	
474		How Rent-All Keeps Their Show on the Road with RAIN RFID	IMPINJ_NXP_WDWASH_00028415 - IMPINJ_NXP_WDWASH_00028419	Diorio		402, 403, 802	
475		Hy-Vee Grocery Cold Chain Monitoring Increases Product Shelf-Life	IMPINJ_NXP_WDWASH_00028420 - IMPINJ_NXP_WDWASH_00028424	Diorio		402, 403, 802	
476		Japan Pallet Rental Tracks Pallets and Assets with RAIN RFID	IMPINJ_NXP_WDWASH_00028425 - IMPINJ_NXP_WDWASH_00028428	Diorio		402, 403, 802	
477		La Chapelle Innovates Supply Chain and In-Store with RAIN RFID	IMPINJ_NXP_WDWASH_00028429 - IMPINJ_NXP_WDWASH_00028433	Diorio		402, 403, 802	
478		LA Marathon Reduces Race Timing Costs with RAIN RFID	IMPINJ_NXP_WDWASH_00028434 - IMPINJ_NXP_WDWASH_00028438	Diorio		402, 403, 802	
479		Levvel Tracks Concrete Blocks for Dike Project with RAIN RFID	IMPINJ_NXP_WDWASH_00028439 - IMPINJ_NXP_WDWASH_00028443	Diorio		402, 403, 802	
480		Love's Travel Stops Uses RAIN RFID to Automate Driver Payments	IMPINJ_NXP_WDWASH_00028444 - IMPINJ_NXP_WDWASH_00028447	Diorio		402, 403, 802	
481		Luik Natie Keeps Frozen Foods Ice-Cold with RAIN RFID	IMPINJ_NXP_WDWASH_00028448 - IMPINJ_NXP_WDWASH_00028453	Diorio		402, 403, 802	
482		Medical Center Ups Efficiency with RAIN RFID Asset Management	IMPINJ_NXP_WDWASH_00028454 - IMPINJ_NXP_WDWASH_00028458	Diorio		402, 403, 802	
483		memove Improves Store Inventory, Reduces Theft with RAIN RFID	IMPINJ_NXP_WDWASH_00028459 - IMPINJ_NXP_WDWASH_00028462	Diorio		402, 403, 802	
484		Meritex Improves Service with RAIN RFID Laundry Management	IMPINJ_NXP_WDWASH_00028463 - IMPINJ_NXP_WDWASH_00028466	Diorio		402, 403, 802	
485		MESNAC Enhances Manufacturing Equipment with RAIN RFID	IMPINJ_NXP_WDWASH_00028467 - IMPINJ_NXP_WDWASH_00028471	Diorio		402, 403, 802	
486		NASA Scientists Use RAIN RFID to Monitor Spacecraft Temperatures	IMPINJ_NXP_WDWASH_00028472 - IMPINJ_NXP_WDWASH_00028475	Diorio		402, 403, 802	

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487		Newark Airport Improves Traveler Experience with RAIN RFID	IMPINJ_NXP_WDWASH_00028476 - IMPINJ_NXP_WDWASH_00028480	Diorio		402, 403, 802	
488		Medical Center Reduces Medication Tracking Errors with RAIN RFID	IMPINJ_NXP_WDWASH_00028481 - IMPINJ_NXP_WDWASH_00028485	Diorio		402, 403, 802	
489		North York General Hospital Improves Operations with RAIN RFID	IMPINJ_NXP_WDWASH_00028486 - IMPINJ_NXP_WDWASH_00028490	Diorio		402, 403, 802	
490		Novart Oy Avoids Costly Shipping Errors with Impinj Platform	IMPINJ_NXP_WDWASH_00028491 - IMPINJ_NXP_WDWASH_00028495	Diorio		402, 403, 802	
491		PAK Automates Laundry Textile Tracking with RAIN RFID	IMPINJ_NXP_WDWASH_00028496 - IMPINJ_NXP_WDWASH_00028499	Diorio		402, 403, 802	
492		Pellenc Maintains Green Spaces with Production Traceability	IMPINJ_NXP_WDWASH_00028500 - IMPINJ_NXP_WDWASH_00028504	Diorio		402, 403, 802	
493		Plexus Drives Manufacturing Efficiencies with RAIN RFID	IMPINJ_NXP_WDWASH_00028505 - IMPINJ_NXP_WDWASH_00028509	Diorio		402, 403, 802	
494		Polaris Saves Thousands with RAIN RFID Automated Manufacturing Solutions	IMPINJ_NXP_WDWASH_00028510 - IMPINJ_NXP_WDWASH_00028513	Diorio		402, 403, 802	
495		Polyplastics Automates Tracking of Raw Materials with RAIN RFID	IMPINJ_NXP_WDWASH_00028514 - IMPINJ_NXP_WDWASH_00028517	Diorio		402, 403, 802	
496		Post Norway Growth with RAIN RFID Infrastructure Upgrade	IMPINJ_NXP_WDWASH_00028518 - IMPINJ_NXP_WDWASH_00028523	Diorio		402, 403, 802	
497		Rady Children's Hospital Tracks Controlled Substances with RAIN RFID	IMPINJ_NXP_WDWASH_00028524 - IMPINJ_NXP_WDWASH_00028528	Diorio		402, 403, 802	
498		Patrizia Pepe Doubles Logistics Efficiency with RAIN RFID	IMPINJ_NXP_WDWASH_00028529 - IMPINJ_NXP_WDWASH_00028533	Diorio		402, 403, 802	
499		Renewable Energy Manufacturer Improves Operations with RAIN RFID	IMPINJ_NXP_WDWASH_00028534 - IMPINJ_NXP_WDWASH_00028537	Diorio		402, 403, 802	
500		Reynolds Achieves ROI in Less Than Three Months with RAIN RFID	IMPINJ_NXP_WDWASH_00028538 - IMPINJ_NXP_WDWASH_00028542	Diorio		402, 403, 802	
501		Roba Metals Automates Track and Trace of Pallets, Speesd Searches	IMPINJ_NXP_WDWASH_00028543 - IMPINJ_NXP_WDWASH_00028547	Diorio		402, 403, 802	
502		SAIC Anji Logistics Halves Inventory Time with RAIN RFID and Drones	IMPINJ_NXP_WDWASH_00028548 - IMPINJ_NXP_WDWASH_00028552	Diorio		402, 403, 802	
503		School District Automates IT Asset Tracking with RAIN RFID	IMPINJ_NXP_WDWASH_00028553 - IMPINJ_NXP_WDWASH_00028557	Diorio		402, 403, 802	
504		The Pub Restaurant Lets Diners Pour Their Own Drinks	IMPINJ_NXP_WDWASH_00028558 - IMPINJ_NXP_WDWASH_00028562	Diorio		402, 403, 802	
505		Hospital Reduces Costs and Saves Thousands with RAIN RFID	IMPINJ_NXP_WDWASH_00028563 - IMPINJ_NXP_WDWASH_00028566	Diorio		402, 403, 802	
506		TopGolf Transforms Golf Driving Ranges with RAIN RFID	IMPINJ_NXP_WDWASH_00028567 - IMPINJ_NXP_WDWASH_00028570	Diorio		402, 403, 802	
507		United Hospital Services Maintains Strict Hygiene and Reduces Waste	IMPINJ_NXP_WDWASH_00028571 - IMPINJ_NXP_WDWASH_00028575	Diorio		402, 403, 802	
508		Undiz Lingerie Literally Flies into Customers' Hands	IMPINJ_NXP_WDWASH_00028576 - IMPINJ_NXP_WDWASH_00028580	Diorio		402, 403, 802	
509		United Technologies Improves Shipping Operations with RAIN RFID	IMPINJ_NXP_WDWASH_00028581 - IMPINJ_NXP_WDWASH_00028585	Diorio		402, 403, 802	
510		University Teaching Clinic Transforms Dentistry Using RAIN RFID	IMPINJ_NXP_WDWASH_00028586 - IMPINJ_NXP_WDWASH_00028589	Diorio		402, 403, 802	
511		USPTO Reduces Manual Labor with IT Asset Management Solution	IMPINJ_NXP_WDWASH_00028590 - IMPINJ_NXP_WDWASH_00028593	Diorio		402, 403, 802	
512		UT Medical Center Automates Supply Management with RAIN RFID	IMPINJ_NXP_WDWASH_00028594 - IMPINJ_NXP_WDWASH_00028599	Diorio		402, 403, 802	

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513		Voestalpine Railway Systems Uses RAIN RFID for Real-Time Railcar Inspection	IMPINJ_NXP_WDWASH_00028600 - IMPINJ_NXP_WDWASH_00028604	Diorio		402, 403, 802	
514		Volvo Deploys RAIN RFID Solution for Automative Manufacturing	IMPINJ_NXP_WDWASH_00028605 - IMPINJ_NXP_WDWASH_00028609	Diorio		402, 403, 802	
515		vXchnge Increases Compliance and Accuracy at Data Centers	IMPINJ_NXP_WDWASH_00028610 - IMPINJ_NXP_WDWASH_00028614	Diorio		402, 403, 802	
516		Photographs of Impinj Employees / Headquarters		Diorio		402, 403	
518	6/12/2001	U.S. Patent No. 6,246,327 ("Eberhardt")		Thompson	X		
519	7/18/2000	U.S. Patent No. 6,091,332 ("Eberhardt '332")		Thompson	X		
521		U.S. Patent Application Publication No. 2011/0139501 ("Ching-San")		Thompson	X		
522	6/27/2016	UCODE 7 Large Pad Project Management Plan	NXP-IMP-NDCAL-00206346 - NXP-IMP-NDCAL-00206370	Zenz	X		
523	12/9/2016	Pre-Assembly Process Delta Qualification Report for Large Pad UCODE 7	NXP-IMP-NDCAL-00206375 - NXP-IMP-NDCAL-00206388	Zenz	X		
524		UCODE 8 Application Sheet	NXP-IMP-NDCAL-00206400 - NXP-IMP-NDCAL-00206400	Zenz	X		
525		UCODE 8 Application Sheet	NXP-IMP-NDCAL-00206494 - NXP-IMP-NDCAL-00206494	Zenz	X		
526		UCODE 8 Large Pad Qualification Report	NXP-IMP-NDCAL-00206401 - NXP-IMP-NDCAL-00206428	Zenz	X		
527		Process Delta Qualification Report UCODE 8	NXP-IMP-NDCAL-00206515 - NXP-IMP-NDCAL-00206530	Zenz	X		
528		UCODE 9 IC Image	NXP-IMP-NDCAL-00208031 - NXP-IMP-NDCAL-00208031	Zenz		F	
529		UCODE 9 Bumped Wafer Layers	NXP-IMP-NDCAL-00209651 - NXP-IMP-NDCAL-00209651	Zenz	X		
530		*NXP USA, Inc. v. Impinj, Inc.*, IPR2020-00516, Paper 6, Patent Owner's Preliminary Response		Thompson		403, 802	
531		*NXP USA, Inc. v. Impinj, Inc.*, IPR2020-00516, Paper 7, Trial Instituted Document		Thompson		402, 403, MIL	
534	12/31/2022	NXP Worldwide Sales Data (through 2022)	NXP-IMP-WDTEX-00024854 - NXP-IMP-WDTEX-00024854	Kindler, NXP		402, 403	
535	12/31/2022	Impinj Invoice Specification (through Q4 2022)	IMPINJ_NXP_WDTEX_00070641 - IMPINJ_NXP_WDTEX_00070641	Dosset, Diorio, Kindler	X		
538		YouTube, 8 Impinj RFID Gen2 for the Distribution Center	NXP-IMP-WDWASH-00022358 - NXP-IMP-WDWASH-00022358	Diorio		402, 403, 802	
539		YouTube, Chainway C72 UHF RFID Reader	NXP-IMP-WDWASH-00022359 - NXP-IMP-WDWASH-00022359	Diorio		402, 403, 802	
540		YouTube, Impinj RFID Solutions for Item-Level Tagging	NXP-IMP-WDWASH-00022362 - NXP-IMP-WDWASH-00022362	Diorio		402, 403, 802	
541		Monza R6 IC		Diorio		NP, 402, 403	
542		Impinj M700 IC		Diorio		NP, 402, 403	
543		NXP UCODE 7 IC		Thompson Durgin		NP, 402, 403	
544		NXP UCODE 8 IC		Thompson Durgin		NP, 402, 403	
545		NXP UCODE 9 IC		Thompson Durgin		NP, 402, 403	
546		Who is Impinj: How We're Innovating IoT with RAIN RFID, https://www.youtube.com/watch?v=_hO4uvvgu1U		Diorio		402, 403, 802	
547		How RAIN RFID Product Authentication Works, https://www.youtube.com/watch?v=RrFcWDeygNc		Diorio		402, 403, 802	

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548		Impinj Celebrating 20 Years, https://www.youtube.com/watch?v=z2S-qt_KJJU		Diorio		402, 403, 802	
549		Competitor Analysis Monza R6	NXP-IMP-WDWASH-00013828 - NXP-IMP-WDWASH-00013839	Zach		402, 403, 802	
550		YouTube, Impinj Retail Interactive Display with InMotion, https://www.youtube.com/watch?v=Of7ADGrhCDs		Diorio		402, 403, 802	
551		YouTube, Impinj Retail Automated Checkout, https://www.youtube.com/watch?v=uLvowW8Glmo		Diorio		402, 403, 802	
552		YouTube, Impinj Retail Inventory Accuracy and Item Location, https://www.youtube.com/watch?v=DuSMHOpz6VU		Diorio		402, 403, 802	
553	5/18/2023	Photograph of Chris Diorio accepting CEO of the Year Award, GeekWire Awards, May 18, 2023		Diorio		402, 403, 802, Repeated Exhibit Number	
599	2003-2004	2003-2004 EPC Global award to Chris Diorio	IMPINJ_NXP_WDWASH_00028720			402; 403; 802	
600	2005	2005 Nasdaq - Ventures All Stars - Venture of the Year award to Impinj	IMPINJ_NXP_WDWASH_00028721			402; 403; 802	
601	38835	2006 EPC Global Tremendous Support Recognition award to Chris Diorio	IMPINJ_NXP_WDWASH_00028722			402; 403; 802	
602	2007	2007 Intel R1000 Industry-First UFH RFID Transceiver award to Impinj	IMPINJ_NXP_WDWASH_00028723			402; 403; 802	
603	2007	2007 RFID Visionary of the Year award to Chris Diorio	IMPINJ_NXP_WDWASH_00028724			402; 403; 802	
604	2011	2011 Inc America's Fastest-Growing Private Companies 5000 award to Impinj	IMPINJ_NXP_WDWASH_00028725			402; 403; 802	
607	2014	2014 Washington's 100 Best Companies to Work For award to Impinj	IMPINJ_NXP_WDWASH_00028728			402; 403; 802	
608	2015	Ace Awards - Innovator of the Yeard and IoT Product of the Year Award to Impinj	IMPINJ_NXP_WDWASH_00028729			402; 403; 802	
609	2015	Frost & Sullivan - RFID Readers in Healthcare award to Impinj	IMPINJ_NXP_WDWASH_00028730			402; 403; 802	
610	2016	Seattle Business Magazine - Tech Impact Awards - Emerging Technology / Productivity award to Impinj	IMPINJ_NXP_WDWASH_00028731			402; 403; 802	
611	2017	2017 Innovator of the Year Award to Chris Diorio	IMPINJ_NXP_WDWASH_00028732			402; 403; 802	
612	2020	Power 100 award to Chris Diorio of Impinj	IMPINJ_NXP_WDWASH_00028733			402; 403; 802	
613	2023	GeekWire Awards 2023 - CEO of the Year Award to Chris Diorio	IMPINJ_NXP_WDWASH_00028734			402; 403; 802	
614	2023	NXP Sales data for 3rd and 4th Quarter of 2023	NXP-IMP-NDCAL-00210261 - NXP-IMP-NDCAL-00210261				
615	2023	POS Data for 2016-2023	NXP-IMP-NDCAL-00210262 - NXP-IMP-NDCAL-00210262				
11A	9/28/2018	Excerpts from TechnInsights CircuitVision Analysis Report of the Analog Circuitry and EEPROM on the NXP UCODE8 SL3S1205 RFID Integrated Circuit (Heinrich NDCA Dep. Ex. 16)				402, 403, 106, 802, F	
332A	3/17/2015	Excerpts from Science Vision Circuit Analysis Report, IPJ-W1700 - Monza R6 Tag Chip (Amtmann NDCA Dep. Ex. 2)				402, 403, 106, 802, 1001, F, MIL	
87A	5/5/2014	Excerpts from Teardown sheet (TechInsights CircuitVision Analysis of the Analog Circuitry on the NXP UCODE 7 RFID IC (Heinrich NDCA Dep. Ex. 17))				106, 802, F, 402, 403	
A		Undisputed Facts		Both Parties		402, 403 (Includes stipulated facts not relevant to trial and/or evidentiary hearing)	
1002	4/25/2017	U.S. Patent No. 9,633,302; Heinrich	None	Subramanian; Heinrich; Diorio; Thompson			

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1004	Multiple	Prosecution file of U.S. Patent No. 9,633,302	IMPINJ_NXP_0000435-IMPINJ_NXP_0000567	Subramanian; Thompson; Heinrich; Diorio			
1005	4/19/2013	Email from H. Heinrich to C. Diorio re "RE: B-stage Adhesive Experiements"	IMPINJ_NXP_0001804-IMPINJ_NXP_0001805	Heinrich; Diorio		F, 402, 403, not relevant to retrial	
1007	1/16/2015	Email from H. Heinrich to T. Wu re: "Beveled RF pads"	IMPINJ_NXP_0001868	Heinrich; Wu; Diorio		402, 403, not relevant to retrial	
1010	3/5/2012	NXP Semiconductors SL3S1204 Product Data Sheet, UCODE 7, Rev. 4.0	IMPINJ_NXP_0001894-IMPINJ_NXP_0001933	Zenz; Subramanian		Not relevant to retrial	
1011	11/19/2018	NXP Semiconductors SL3S1205_15 UCODE 8/8m Product data sheet, Rev. 3.2	IMPINJ_NXP_0001934-IMPINJ_NXP_0001969	Zenz; Subramanian		Not relevant to retrial	
1012	9/28/2018	Tech Insights CircuitVision Analysis Report of the Analog Circuitry and EEPROM on the NXP UCODE8 SL3S1205 RFID Integrated Circuit	IMPINJ_NXP_0002004-IMPINJ_NXP_0002127	Heinrich; Oliver; Diorio		403, not relevant to retrial	
1013	5/5/2014	Tech Insights CircuitVision Analysis of the Analog Circuitry on the NXP UCODE 7 RFID IC	IMPINJ_NXP_0002128-IMPINJ_NXP_0002242	Heinrich; Oliver; Subramanian; Thompson		403, not relevant to retrial	
1017	Undated	UCODE 9 (AS-5607 - SL3S1206 Bump Images	IMPINJ_NXP_0046525-IMPINJ_NXP_0046529	Subramanian; Thompson		F, 402, 403, 802 not relevant to retrial	
1021	November 2017	Japan Trip Notes Nov 13-17 2017	IMPINJ_NXP_0046565-IMPINJ_NXP_0046574	Diorio		F, 402, 802, not relevant to retrial	
1028	2017	17Q2 China Trip Notes	IMPINJ_NXP_0046656-IMPINJ_NXP_0046670	Diorio, Oliver		F, 402, 802, not relevant to retrial	
1029	October 2016	Trip report summary from Todd H, Carl B, and Goetz P travel to Europe on Oct 18-21, 2016	IMPINJ_NXP_0046671-IMPINJ_NXP_0046681	Dossett; Diorio		F, 402, 802, not relevant to retrial	
1034	Undated	Impinj presentation: Q117 Monza Summit, Product Management	IMPINJ_NXP_0046692	Dossett; Diorio		F, 402, 403, not relevant to retrial	
1035	4/3/2017	Impinj presentation: Q217 Monza Summit	IMPINJ_NXP_0046693	Dossett; Diorio		F, 402, 403, not relevant to retrial	
1036	7/11/2017	Impinj presentation: 3Q17 Monza Summit	IMPINJ_NXP_0046694	Dossett; Diorio		Not relevant to retrial	
1037	10/5/2017	Impinj presentation: 4Q17 Monza Summit	IMPINJ_NXP_0046695	Diorio		Not relevant to retrial	
1038	1/10/2018	Impinj presentation: 1Q18 Monza Summit	IMPINJ_NXP_0046696	Diorio		F, 402, 403, not relevant to retrial	
1039	4/18/2018	Impinj presentation: 2Q18 Monza Summit	IMPINJ_NXP_0046697	Dossett; Diorio		F, 402, 403, not relevant to retrial	
1040	7/25/2018	Impinj presentation: 3Q18 Monza Summit	IMPINJ_NXP_0046698	Dossett; Diorio		F, 402, 403, not relevant to retrial	
1041	10/17/2018	Impinj presentation: 4Q18 Monza Summit	IMPINJ_NXP_0046699	Diorio		F, 402, 403, not relevant to retrial	
1042	1/22/2019	Impinj presentation: 1Q19 Monza Summit	IMPINJ_NXP_0046700	Dossett; Diorio		F, 402, 403, not relevant to retrial	
1043	4/17/2019	Impinj presentation: 2Q19 Silicon Summit	IMPINJ_NXP_0046701	Mecklai		F, 402, 403, not relevant to retrial	
1044	7/15/2019	Impinj presentation: 3Q19 Silicon Summit	IMPINJ_NXP_0046702	Dossett; Diorio		F, 402, 403, not relevant to retrial	

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1045	10/21/2020	Impinj presentation: 4Q20 Endpoint IC Summit	IMPINJ_NXP_0046836-IMPINJ_NXP_0046888	Subramanian; Thompson		Not relevant to retrial	
1046	4/20/2021	Impinj presentation: 2Q21 Endpoint IC Summit	IMPINJ_NXP_0046958-IMPINJ_NXP_0047015	Diorio		Not relevant to retrial	
1047	7/15/2021	Impinj presentation: 3Q21 Endpoint IC	IMPINJ_NXP_0047016-IMPINJ_NXP_0047077	Dossett; Diorio		Not relevant to retrial	
1077	4/10/2021	Impinj presentation: Endpoint IC Strategy	IMPINJ_NXP_0047253-IMPINJ_NXP_0047293	Diorio; Subramanian; Thompson		Not relevant to retrial	
1078	8/30/2013	Impinj presentation: Mustang Go/No-go	IMPINJ_NXP_0047294-IMPINJ_NXP_0047357	Diorio; Subramanian; Thompson	X		
1140	11/30/2016	NXP Semiconductors SL3S10x4 UCODE 7xm-1k, UCODE 7xm-2k, and UCODE 7xm+ product data sheet, Rev. 3.3	NXP-IMP-NDCAL-00000206-NXP-IMP-NDCAL-00000238	Zenz; Subramanian		Not relevant to retrial	
1141	Undated	NTAG Product Features Summary	NXP-IMP-NDCAL-00000312	Zenz		F, 402, 403, not relevant to retrial	
1142	3/5/2019	NXP Semiconductors SL3S1204 UCODE 7 Product data sheet, Rev. 4.0	NXP-IMP-NDCAL-00000314-NXP-IMP-NDCAL-00000353	Zenz; Subramanian; Thompson		Not relevant to retrial	
1143	10/28/2019	NXP Semiconductors SL3S1205_15 UCODE 8/8m product data sheet, Rev. 3.3	NXP-IMP-NDCAL-00000354-NXP-IMP-NDCAL-00000389	Amtmann; Brandl; Thompson; Subramanian		Not relevant to retrial	
1144	10/28/2019	Annotated excerpt from NXP SL3S1205_15 - UCODE 8/8m Data Sheet depicting Wafer layout with figure drawing highlighted in yellow of bump size's trenches	NXP-IMP-NDCAL-00000360-NXP-IMP-NDCAL-00000361	Thompson		402, not relevant to retrial	
1145	3/6/2019	NXP Semiconductors SL3S1214 UCODE 7m product data sheet, Rev. 3.4	NXP-IMP-NDCAL-00000390-NXP-IMP-NDCAL-00000423	Amtmann; Brandl; Zenz; Subramanian; Thompson		Not relevant to retrial	
1147	2009	Cai, Xiong-Hui, “Assembly of flexible RFID tag inlays with anisotropic conductive paste (ACP),” Circuit World 35(4): 40-45 (2009)	NXP-IMP-NDCAL-00000436-NXP-IMP-NDCAL-00000442	Subramanian		F, 402, Not within scope of retrial	
1148	August 2010	Finkenzeller, "RFID Handbook", Wiley, 3:1-462, August 2010	NXP-IMP-NDCAL-00000492-NXP-IMP-NDCAL-00000971	Subramanian		F, 402, Not within scope of retrial	
1151	8/1/1999	Gilleo et al., "Towards a better understanding of underfill encapsulation for flip chip technology: proposed developments for the future," Microelectronics International 16:2 (1999), pp. 39-43	NXP-IMP-NDCAL-00001676-NXP-IMP-NDCAL-00001681	Subramanian		F, 402, Not within scope of retrial	
1154	2005	Landt, Jeremy, “The History of RFID,” IEEE Potentials 24(4):8-11, (Oct.-Nov. 2005)	NXP-IMP-NDCAL-00001809-NXP-IMP-NDCAL-00001812	Subramanian		F, 402, Not within scope of retrial	
1159	5/19/2005	U.S. Patent Application Publication No. 2005/0104732; Furter et al.	NXP-IMP-NDCAL-00002146-NXP-IMP-NDCAL-00002157	Subramanian		F, 402, Not within scope of retrial	
1160	3/16/2006	U.S. Patent Appl. Publ. No. 2006/0057763; Teo et al.	NXP-IMP-NDCAL-00002158-NXP-IMP-NDCAL-00002169	Subramanian		F, 402, Not within scope of retrial	
1161	11/19/2009	U.S. Patent Application Publication No. 2009/0283602; Rogy et al.	NXP-IMP-NDCAL-00002364-NXP-IMP-NDCAL-00002375	Subramanian		F, 402, Not within scope of retrial	

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1162	6/12/2001	U.S. Patent No. 6,246,327; Eberhardt	NXP-IMP-NDCAL-00002711-NXP-IMP-NDCAL-00002719	Subramanian	X		
1164	8/25/2009	U.S. Patent No. 7,578,053; Nishigawa et al.	NXP-IMP-NDCAL-00002930-NXP-IMP-NDCAL-00002951	Subramanian		F, 402, Not within scope of retrial	
1169	1/1/2000	Zenner, Robert Lawrence David, "Integrated Circuit Chip Interconnect Performance using Anisotropically Conducting Adhesive Films," (Jan. 2000)	NXP-IMP-NDCAL-00003906-NXP-IMP-NDCAL-00004084	Subramanian		F, 402, Not within scope of retrial	
1171	11/19/2018	NXP Semiconductors SL3S1205_15 UCODE 8/8m Product data sheet SL3S1205_15, Rev. 3.2	NXP-IMP-NDCAL-00004173-NXP-IMP-NDCAL-00004208	Kodritsch; Zenz; Zach		Not relevant to retrial	
1172	10/20/2016	NXP Semiconductors Validation, Characterization and Qualification Report - UCODE 8; Doc Rev 0.1	NXP-IMP-NDCAL-00004529-NXP-IMP-NDCAL-00004634	Zenz	X		
1173	April 2017	NXP UCODE 8 Fact Sheet - Omnichannel Retail Data at unmatched Speed and Accuracy	NXP-IMP-NDCAL-00004735-NXP-IMP-NDCAL-00004736	Zenz; Kodritsch; Zach		Not relevant to retrial	
1174	3/2019	NXP presentation: Improving the product journey with UCODE® 8	NXP-IMP-NDCAL-00004829	Kodritsch		Not relevant to retrial	
1175	6/20/2012	Customer Requirements Specification, BiC UCODE, Doc Rev 4 Approved	NXP-IMP-NDCAL-00004830-NXP-IMP-NDCAL-00004847	Bischof; Kodritsch		Not relevant to retrial	
1197	7/20/2015	UCODE 8 Update Meeting	NXP-IMP-NDCAL-00005232	Kodritsch; Zach		Not relevant to retrial	
1214	10/17/2016	NXP Semiconductors System Requirements for UCODE 8, Rev 1.0	NXP-IMP-NDCAL-00005836-NXP-IMP-NDCAL-00005848	Zenz		Not relevant to retrial	
1219	Undated	Excel: UCODE 7 Large Pad Summary	NXP-IMP-NDCAL-00048182	Subramanian		Not relevant to retrial	
1222	Undated	NXP presentation: NXP - HID	NXP-IMP-NDCAL-00206213	Kodritsch		F, 402, 403, 802, not relevant to retrial	
1229	3/26/2014	Impinj Enduro Technology Overview; Rev. 2.0	NXP-IMP-NDCAL-00206329-NXP-IMP-NDCAL-00206340	Diorio; Heinrich; Zenz; Kodritsch; Zach	X		
1230	6/27/2016	NXP Semiconductors Outline Project Plan / Project Management Plan for Large Pad UCODE7, Rev. 2.0	NXP-IMP-NDCAL-00206346-NXP-IMP-NDCAL-00206370	Kodritsch; Zenz		Not relevant to retrial	
1231	Undated	NXP presentation slide: Mega Bump UCODE 7 organizational chart	NXP-IMP-NDCAL-00206371	Kodritsch; Zenz		F, 402, 403, not relevant to retrial	
1232	12/9/2016	NXP Semiconductor Pre-Assembly Process Delta Qualification Report for Large Pad Ucode7	NXP-IMP-NDCAL-00206375-NXP-IMP-NDCAL-00206388	Subramanian; Zenz		not relevant to retrial	
1233	12/24/2016	NXP presentation: Product Analysis Report, UCODE 7 Large Pads	NXP-IMP-NDCAL-00206389-NXP-IMP-NDCAL-00206398	Subramanian; Zenz		not relevant to retrial	
1234	3/5/2018	NXP presentation: Product Analysis Report, U8-PTC-Large-Pad Qual	NXP-IMP-NDCAL-00206429	Subramanian; Zenz		not relevant to retrial	
1235	Undated	Bump Mask Drawings	NXP-IMP-NDCAL-00206456-NXP-IMP-NDCAL-00206462	Subramanian; Zenz		not relevant to retrial	
1243	6/16/2011	U.S. Patent Application Publication No. 2011/0139501; Ching-San et al.	NXP-IMP-NDCAL-00206971-NXP-IMP-NDCAL-00206979	Subramanian	X		
1244	6/16/2011	U.S. Patent Application Publication No. 2011/0139878; Grasset	NXP-IMP-NDCAL-00206980-NXP-IMP-NDCAL-00206987	Subramanian		F, 402, Not within scope of retrial	
1246	8/2/2012	U.S. Patent Application Publication No. 2012/0193804; Grasset	NXP-IMP-NDCAL-00207019-NXP-IMP-NDCAL-00207027	Subramanian		F, 402, Not within scope of retrial	

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1247	9/8/1998	U.S. Patent No. 5,804,882; Tsukagoshi et al.	NXP-IMP-NDCAL-00207069-NXP-IMP-NDCAL-00207079	Subramanian		F, 402, Not within scope of retrial	
1248	8/22/2000	U.S. Patent No. 6,107,920; Eberhardt et al.	NXP-IMP-NDCAL-00207080-NXP-IMP-NDCAL-00207094	Subramanian		F, 402, Not within scope of retrial	
1249	2/6/2001	U.S. Patent No. 6,184,581; Cornell et al.	NXP-IMP-NDCAL-00207103-NXP-IMP-NDCAL-00207109	Subramanian		F, 402, Not within scope of retrial	
1250	9/24/2009	International Patent Publication No. WO 2009/115673; Grasset (Translation & Original)	NXP-IMP-NDCAL-00207378-NXP-IMP-NDCAL-00207424	Subramanian		F, 402, Not within scope of retrial	
1251	2/10/2011	International Patent Publication No. WO 2011/015732; Grasset (Translation & Original)	NXP-IMP-NDCAL-00207452-NXP-IMP-NDCAL-00207503	Subramanian		F, 402, Not within scope of retrial	
1252	1/25/1994	U.S. Patent No. 5,281,855; Hadden et al.	NXP-IMP-NDCAL-00207799-NXP-IMP-NDCAL-00207806	Subramanian		F, 402, Not within scope of retrial	
1255	12/15/2020	NXP Semiconductors SL3S1206 UCODE 9 Product data sheet, Rev. 3.0	NXP-IMP-NDCAL-00207839-NXP-IMP-NDCAL-00207867	Zenz; Subramanian		Not relevant to retrial	
1257	August 2018	NXP UCODE 9 - Concept Working Document	NXP-IMP-NDCAL-00208058	Zenz		Not relevant to retrial	
1261	3/24/2021	NXP presentation: UCODE 9 - Tageos samples	NXP-IMP-NDCAL-00208205	Zenz		F, 402, 403, 802, not relevant to retrial	
1262	12/3/2020	NXP Semiconductors SL3S1206 UCODE 9 Preliminary Data Sheet, Rev. 2.0	NXP-IMP-NDCAL-00208318-NXP-IMP-NDCAL-00208346	Zenz		Not relevant to retrial	
1263	12/15/2020	NXP Semiconductors SL3S1206 UCODE 9 Data Sheet, Rev. 3.0	NXP-IMP-NDCAL-00208347-NXP-IMP-NDCAL-00208375	Zenz		Not relevant to retrial	
1270	Undated	UCODE 8 and UCODE 9 pad layout	NXP-IMP-NDCAL-00208499	Zenz		Not relevant to retrial	
1287	Undated	Technical Information for Monopox AC6530	NXP-IMP-NDCAL-00209150-NXP-IMP-NDCAL-00209152	Subramanian		F, 402, 403, 802, not relevant to retrial	
1289	Undated	UCODE 7 photograph of chip with bumps without large pads	NXP-IMP-NDCAL-00209510	Zenz; Subramanian		F, 402, 403, not relevant to retrial	
1290	Undated	UCODE 8 Large Pad photograph	NXP-IMP-NDCAL-00209511	Zenz; Subramanian		Not relevant to retrial	
1292	7/24/2009	HTCICC64 HITAG µ RO64 transponder IC Product data sheet, Rev. 3.1	NXP-IMP-NDCAL-00209666-NXP-IMP-NDCAL-00209678	Zenz; Kodritsch; Subramanian; Zach		F, 402, 403, MIL, not relevant to retrial	
1293	3/18/2010	NXP - HITAG µ Product Data Sheet ISO 18000 transponder IC - 184430 Rev. 3.0	NXP-IMP-NDCAL-00209679-NXP-IMP-NDCAL-00209722	Zenz; Kodritsch; Subramanian; Zach		F, 402, 403, MIL, not relevant to retrial	
1310	2009	NXP low-frequency HITAG-µ Ics Fact Sheet - 4th generation HITAG for advanced, low-cost RFID	None	Zenz; Subramanian; Zach		F, 402, 403, MIL, not relevant to retrial	

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1311	8/15/2022	NXP Semiconductors SL3S1203_1213 UCODE G2IL and G2IL+ Product Data Sheet, Rev. 4.4	None	Zenz; Subramanian; Zach		F, 402, 403, not relevant to retrial	
1312	8/15/2022	NXP Semiconductors SL3ICS1002/1202 UCODE G2XM and G2XL Product Data Sheet, Rev. 3.8	None	Zenz; Subramanian; Zach		F, 402, 403, not relevant to retrial	
1313	12/2/2021	NXP Semiconductors SL3S1205_15 UCODE 8/8m Product Data Sheet, Rev. 3.6	None	Zenz		Not relevant to retrial	
1314	11/11/2013	SL3ICS1002/1202 UCODE G2XM and G2XL Product data sheet, Rev. 3.8 (available at http://www.orangetags.com/wpcontent/downloads/datasheet/NXP/SL3S1203_1213.pdf)	None	Zenz		F, 402, 403, not relevant to retrial	
1318	8/15/2022	Curriculum Vitae of Vivek Subramanian	None	Subramanian		F, 802	
1339	Undated	Drawing representing surface of an IC	None	Subramanian		F, 402, 403	
1340	1/21/2015	Sketch of hypothetical top view with orange antenna contacts and blue channel for adhesive between them	None	Thompson; Subramanian		F, 402, 403	
1369	6/25/1991	U.S. Patent No. 5,025,550; Zirbes et al.	None	Subramanian		F, 402, 403, not relevant to retrial	
1376	5/4/2017	Impinj, Inc. Q1 2017 Earnings Call Transcript, May 4, 2017	None	Diorio		F, 402, 802, not relevant to retrial	
1377	8/3/2017	Impinj, Inc. Q2 2017 Earnings Call Transcript, August 3, 2017	None	Diorio		F, 402, 802, not relevant to retrial	
1378	11/1/2017	Impinj, Inc. Q3 2017 Earnings Call Transcript, November 1, 2017	None	Diorio		F, 402, 802, not relevant to retrial	
1379	2/15/2018	Impinj, Inc. Q4 2017 Earnings Call Transcript, February 15, 2018	None	Diorio		F, 402, 802, not relevant to retrial	
1380	5/7/2018	Impinj First Quarter Earnings Conference Call transcript, May 7, 2018	None	Diorio		F, 402, 802, not relevant to retrial	
1381	9/13/2018	Impinj, Inc. Q2 2018 Earnings Call Transcript, September 13, 2018	None	Diorio		F, 402, 802, not relevant to retrial	
1382	10/29/2018	Impinj, Inc. Q3 2018 Earnings Call Transcript, October 29, 2018	None	Diorio		F, 402, 802, not relevant to retrial	
1383	2/20/2019	Impinj, Inc. Q4 2018 Earnings Call Transcript, February 20, 2019	None	Diorio		F, 402, 802, not relevant to retrial	
1384	4/29/2019	Impinj, Inc. Q1 2019 Earnings Call Transcript, April 29, 2019	None	Diorio		F, 402, 802, not relevant to retrial	
1385	7/29/2019	Impinj, Inc. Q2 2019 Earnings Call Transcript, July 29, 2019	None	Diorio		F, 402, 802, not relevant to retrial	
1386	11/4/2019	Impinj, Inc. Q3 2019 Earnings Call Transcript, November 4, 2019	None	Diorio		F, 402, 802, not relevant to retrial	
1387	3/2/2020	Impinj, Inc. Q4 2019 Earnings Call Transcript, March 2, 2020	None	Diorio		F, 402, 802, not relevant to retrial	
1388	4/27/2020	Impinj, Inc. Q1 2020 Earnings Call Transcript, April 27, 2020	None	Diorio		F, 402, 802, not relevant to retrial	
1389	7/29/2020	Impinj, Inc. Q2 2020 Earnings Call Transcript, July 29, 2020	None	Diorio		F, 402, 802, not relevant to retrial	
1390	10/28/2020	Impinj, Inc. Q3 2020 Earnings Call Transcript, October 28, 2020	None	Diorio		F, 402, 802, not relevant to retrial	
1391	2/9/2021	Impinj Fourth-Quarter 2021 Earnings Conference Call Transcript, February 9, 2021	None	Diorio		F, 402, 802, not relevant to retrial	

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1392	2/10/2021	Impinj, Inc. Q4 2020 Earnings Call Transcript, February 10, 2021	None	Diorio		F, 402, 802, not relevant to retrial	
1393	4/28/2021	Impinj, Inc. Q1 2021 Earnings Call Transcript, April 28, 2021	None	Diorio		F, 402, 802, not relevant to retrial	
1394	7/28/2021	Impinj, Inc. Q2 2021 Earnings Call Transcript, July 28, 2021	None	Diorio		F, 402, 802, not relevant to retrial	
1395	10/27/2021	Impinj, Inc. Q3 2021 Earnings Call Transcript, October 27, 2021	None	Diorio		F, 402, 802, not relevant to retrial	
1396	4/27/2022	Impinj, Inc. Q1 2022 Earnings Call Transcript, April 27, 2022	None	Diorio		F, 402, 802, not relevant to retrial	
1397	7/27/2022	Impinj, Inc. Q2 2022 Earnings Call Transcript, July 27, 2022	None	Diorio		F, 402, 802, not relevant to retrial	
1402	Undated	NXP History (https://www.nxp.com/company/about-nxp/history:NXP-HISTORY)	None	Kodritsch		F, 402, 802	
1403	Undated	We Are NXP (https://www.nxp.com/company/about-nxp/we-are-nxp:WE-ARE-NXP)	None	Kodritsch		F, 402, 803	
1404	Undated	About NXP (https://www.nxp.com/company/about-nxp:ABOUT-NXP)	None	Kodritsch		F, 402, 804	
1405	Undated	NXP in the United States (https://www.nxp.com/company/about-nxp/worldwide-locations/united-states:USA)	None	Kodritsch		F, 402, 805	
1408	11/17/2021	Impinj Amended Infringement Contentions Ex. F-1 - Infringement Claim Chart for U.S. Patent No. 9,633,302	None	Subramanian		Not relevant to retrial	
1413	4/25/2022	Impinj, Inc.'s Second Supplemental Responses to NXP USA, Inc.'s First Set of Interrogatories (Nos. 1-2)	None	Heinrich; Diorio; Thompson; Subramanian	X		
1414	4/25/2022	Impinj, Inc.'s Supplemental Response to NXP USA, Inc.'s Third Set of Interrogatories (Nos. 5-11)	None	Diorio; Dossett; Heinrich	X		
1415	9/27/2021	Impinj, Inc.'s Objections and Responses to NXP USA, Inc.'s Third Set of Interrogatories (Nos. 5-12)	None	Diorio; Dossett; Heinrich	X		
1419	3/31/2022	Designated testimony from the deposition of Kurt Bischof, taken on March 31, 2022 (N.D. Cal.)	None	Bischof			
1424	8/5/2022	Designated testimony from the deposition of Paul Davies, taken on August 5, 2022 (W.D. Tex.)	None	Davies			
1425	4/13/2022	Designated testimony from the deposition of Christopher Diorio, taken on April 13, 2022 (N.D. Cal.)	None	Diorio			
1426	4/14/2022	Designated testimony from the deposition of Christopher Diorio, taken on April 14, 2022 (N.D. Cal.)	None	Diorio			
1427	4/25/2022	Designated testimony from the deposition of Jeff Dossett, taken on April 25, 2022 (N.D. Cal.)	None	Dossett			
1428	11/14/2022	Designated testimony from the deposition of Jeff Dossett, taken on November 14, 2022 (W.D. Wash.)	None	Dossett			
1429	4/20/2022	Designated testimony from the deposition of Harley Heinrich, taken on April 20, 2022 (N.D. Cal.)	None	Heinrich			
1430	4/21/2022	Designated testimony from the deposition of Harley Heinrich, taken on April 21, 2022 (N.D. Cal.)	None	Heinrich			
1432	5/10/2022	Designated testimony from the deposition of Ralf Kodritsch, taken on May 10, 2022 (N.D. Cal.)	None	Kodritsch			
1436	4/20/2022	Designated testimony from the deposition of Ron Oliver, taken on April 20, 2022 (N.D. Cal.)	None	Oliver			

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1437	4/21/2022	Designated testimony from the deposition of Ron Oliver, taken on April 21, 2022 (N.D. Cal.)	None	Oliver			
1438	2/1/2023	Designated testimony from the deposition of Ron Oliver, taken on February 1, 2023 (W.D. Tex.)	None	Oliver			
1443	4/20/2022	Designated testimony from the deposition of Nigel Stott, taken on April 20, 2022 (N.D. Cal.)	None	Stott			
1446	5/13/2022	Designated testimony from the deposition of Hermann Zach, taken on May 13, 2022 (N.D. Cal.)	None	Zach			
1447	1/20/2023	Designated testimony from the deposition of Hermann Zach, taken on January 20, 2023 (W.D. Tex.)	None	Zach			
1448	4/6/2022	Designated testimony from the deposition of Christian Zenz, taken on April 6, 2022 (N.D. Cal.)	None	Zenz			
1456	10/22/2012	UCODE BIC Floorplanning	NXP-IMP-NDCAL-00209054 - NXP-IMP-NDCAL-00209071	Zenz		402, 403, not relevant to invalidity retrial	
1457	6/27/2016	Outline Project Plan / Project Management Plan Large Pad UCODE 7	NXP-IMP-NDCAL-00206346 - NXP-IMP-NDCAL-00206370	Zenz		402, 403, not relevant to invalidity retrial	
1458	12/9/2004	Optimized process flow for ultra-thin chips, made of commercialized wafer	NXP-IMP-NDCAL-00004889 - NXP-IMP-NDCAL-00004909	Zenz		402, 403, not produced, not relevant to invalidity retrial	
1459	6/11/2019	Q&A regarding lawsuit	IMPINJ_NXP_0047176 - IMPINJ_NXP_0047177	Diorio		402, 403, not relevant to invalidity retrial	
1460	6/5/2019	CEO Letter: Patent-Infirngement Lawsuit Filed Against NXP	IMPINJ_NXP_0046684 - IMPINJ_NXP_0046686	Diorio		402, 403, not relevant to invalidity retrial	
1461	10/26/2022	Impinj, Inc. Q3 2022 Earnings Call Transcript, October 26, 2022	None	Diorio		402, 403, not produced, not relevant to invalidity retrial	
1462	2/8/2023	Impinj, Inc. Q4 2022 Earnings Call Transcript, February 8, 2023	None	Diorio		402, 403, not produced, not relevant to invalidity retrial	